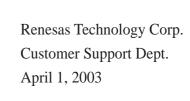
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# 2SD1113(K)

# Silicon NPN Triple Diffused

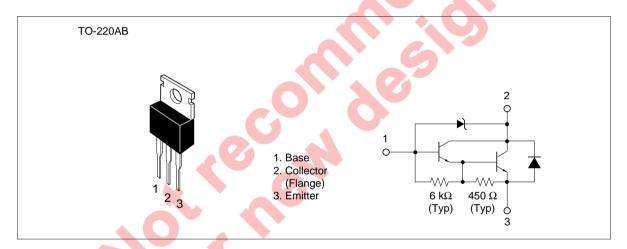


ADE-208-903 (Z) 1st. Edition September 2000

### **Application**

Igniter

#### **Outline**



### **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	300	V
Collector to emitter voltage	$V_{\text{CEO}}$	300	V
Emitter to base voltage	$V_{EBO}$	7	V
Collector current	I <sub>c</sub>	6	A
Collector peak current	I <sub>C(peak)</sub>	10	A
Collector power dissipation	P <sub>c</sub> *1	40	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

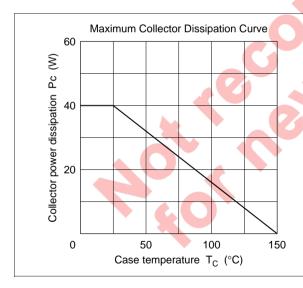
Note: 1. Value at  $T_c = 25^{\circ}C$ .

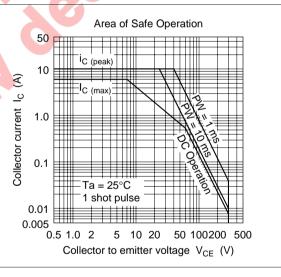
# 2SD1113(K)

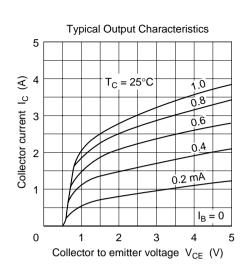
## **Electrical Characteristics** (Ta = 25°C)

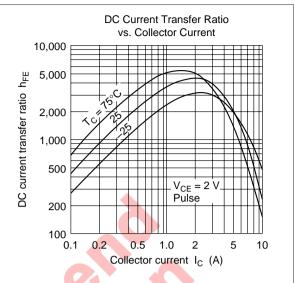
Symbol	Min	Тур	Max	Unit	Test conditions
$V_{(BR)CBO}$	300	_	500	V	$I_{\rm C} = 0.1 \text{ mA}, I_{\rm E} = 0$
$V_{\text{CEO(sus)}}$	300	_	_	V	I <sub>C</sub> = 3 A, PW = 50 μs, f = 50 Hz, L = 10 mH
$V_{(BR)EBO}$	7	_	_	V	$I_{\rm E} = 50 \text{ mA}, I_{\rm C} = 0$
I <sub>CEO</sub>	_	_	100	μΑ	V <sub>CE</sub> = 300 V, R <sub>BE</sub> = ∞
h <sub>FE</sub>	500	_	_		$V_{CE} = 2 \text{ V}, I_{C} = 4 \text{ A}^{*1}$
$V_{\text{CE(sat)}}$	_	_	1.5	V	$I_{\rm c} = 4 \text{ A}, I_{\rm B} = 40 \text{ mA}^{*1}$
$V_{BE(sat)}$	_	_	2.0	V	$I_{\rm C} = 4 \text{ A}, I_{\rm B} = 40 \text{ mA}^{*1}$
t <sub>on</sub>	_	2.0	_	μs	$I_{\rm C} = 4 \text{ A}, I_{\rm B1} = -I_{\rm B2} = 40 \text{ mA}$
t <sub>off</sub>	_	23		μs	$I_{\rm C} = 4 \text{ A}, I_{\rm B1} = -I_{\rm B2} = 40 \text{ mA}$
	$V_{(BR)CBO}$ $V_{CEO(sus)}$ $V_{(BR)EBO}$ $I_{CEO}$ $h_{FE}$ $V_{CE(sat)}$ $V_{BE(sat)}$ $t_{on}$	V <sub>(BR)CBO</sub> 300           V <sub>CEO(sus)</sub> 300           V <sub>(BR)EBO</sub> 7           I <sub>CEO</sub> —           h <sub>FE</sub> 500           V <sub>CE(sat)</sub> —           V <sub>BE(sat)</sub> —           t <sub>on</sub> —	V <sub>(BR)CBO</sub> 300       —         V <sub>CEO(sus)</sub> 300       —         V <sub>(BR)EBO</sub> 7       —         I <sub>CEO</sub> —       —         h <sub>FE</sub> 500       —         V <sub>CE(sat)</sub> —       —         V <sub>BE(sat)</sub> —       —         t <sub>on</sub> —       2.0	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	$\begin{array}{cccccccccccccccccccccccccccccccccccc$

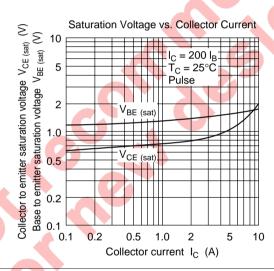
Note: 1. Pulse test.











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